		2004/06/16	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	chip-to-package and I/O	31	BRS	0
		2004/06/15 16:58	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	chip-to-package with I/O	6	BRS	ග
		2004/06/15 16:57	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	chip-to-package with test\$3	ω	BRS	4
		2004/06/15 17:18	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	chip-to-package with connect\$5 with test\$3	ω	BRS	ω
		2004/06/15 16:56	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	("6397361").PN.	2	IS&R	Ν
		2004/06/16	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	("6724210").PN.	2	IS&R	T
Error Definiti	Comments	Time Stamp	DBs	Search Text	Hits	Туре	m ₁

	Туре	Hits	Search Text	DBs	Time Stamp	Comments
7	BRS	4	chip-to-package and I/O and transition	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/15 17:01	
8	BRS	2	chip-to-package with connection with I/O	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/15	
9	BRS	4	chip-to-package with connection and I/O with semiconductor\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/15	
10	BRS	84	chip-to-package	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/15	
11	BRS	2	324/\$.ccls. and chip-to-package and test\$3 with semiconductor\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/15 17:05	
12	BRS	4	chip-to-package and test\$3 with semiconductor\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/15	1

	Туре	Hits	Search Text	DBs	Time Stamp	Comments D	Error Definiti on
13	BRS	337	test\$3 with semiconductor\$1 with i/o	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/15 17:08		
14	BRS	26	test\$3 with semiconductor\$1 with i/o with connection	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/15		
15	BRS	41	chip-to-package and test\$3 with semiconductor\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/15 17:23		
16	BRS	17	<pre>chip-to-package and test\$3 with (wafer\$1 or semiconductor\$1 or integrated adj circuit\$1 or Ic\$1)</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/15 17:24		
17	BRS	· 8	<pre>chip-to-package and test\$3 with (wafer\$1 or semiconductor\$1 or integrated adj circuit\$1 or Ic\$1) and I/O</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/15 17:24		
18	BRS	⊢	"6556621".PN.	USPAT	2004/06/16 09:05		
19	BRS	H	"6115113".PN.	USPAT	2004/06/16 09:05		
20	BRS	-	"5418820".PN.	USPAT	2004/06/16		

•	Туре	Hits	Search Text	DBs	Time Stamp	Comments 1	Error Definiti on
21	BRS	ω	test\$3 with (semiconductor adj chip) with (semiconductor adj package) with connect\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	;2004/06/16 09:27		
22	BRS	43230	test\$3 with semiconductor chip with package with connect\$5 with I/O	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/16 09:28		
23	BRS	ω	test\$3 with (wafer\$1 or IC\$1 or (integrated adj circuit\$1) or semiconductor\$1) with chip with package with connect\$5 with I/O	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	;2004/06/16 09:33		
2 4	BRS	23	test\$3 with (wafer\$1 or IC\$1 or (integrated adj circuit\$1) or semiconductor\$1) with chip with package with connect\$5 with (input/output or I/O)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/16 10:03		
ν σ	BRS	26	test\$3 with (wafer\$1 or IC\$1 or (integrated adj circuit\$1) or semiconductor\$1) with chip\$1 with package\$1 with connect\$5 with (input/output or I/O)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/16 09:45		

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н	Туре	Hits	Search Text	DBs	Time Stamp	Comments	Definiti on
26 B	BRS	ω	test\$3 with (wafer\$1 or IC\$1 or (integrated adj circuit\$1) or semiconductor\$1) with chip\$1 with package\$1 with connect\$5 with	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/16		
			\$3 with (wafer\$1				
27 B.	BRS	8	r (integrated a t\$1) or nductor\$1) and with package\$ onnect\$5 with /output or I/O) se with time	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/16 09:39		
28 B	BRS	152	test\$3 with (wafer\$1 or IC\$1 or (integrated adj circuit\$1) or semiconductor\$1) and chip\$1 with package\$1 with connect\$5 with (input/output or I/O)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/16		
29 B	BRS	7	test\$3 with (wafer\$1 or IC\$1 or (integrated adj circuit\$1) or semiconductor\$1) and chip\$1 with package\$1 with connect\$5 with (input/output or I/O) and transition with signal\$1	USPAT; US-PGPUB; EPO;; JPO; DERWENT; IBM_TDB	;2004/06/16 09:51		

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	Туре	Hits	Search Text	DBs	Time Stamp
30	BRS	7	6397361.uref.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/16 09:54
31	BRS	7	6397361.uref. and (wafer\$1 or IC\$1 or (integrated adj circuit\$1) or semiconductor\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/16 09:54
32	BRS	80	test\$3 with (wafer\$1 or IC\$1 or (integrated adj circuit\$1) or semiconductor\$1) and I/O with receiver with driver	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/16 10:16
ω	BRS	7	test\$3 with (wafer\$1 or IC\$1 or (integrated adj circuit\$1) or semiconductor\$1) and I/O with receiver with driver and perform\$3 with connect\$5 with (I/O or input/output)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/16 10:11
ω 4	BRS	N	6057698.uref.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/16 10:11

-	Туре	Hits	Search Text test\$3 with (wafer\$1 or	DBs	
ယ Մ	BRS	36	with (wafer\$1 or (integrated adj :\$1) or aductor\$1) and I/O eceiver with driver onnect\$5	USPAT; US-PGPUB; EPO JPO; DERWENT; IBM_TDB	EPO; ENT;
36	BRS	26	test\$3 with (wafer\$1 or IC\$1 or (integrated adj circuit\$1) or semiconductor\$1) and I/O with receiver with driver with connect\$5 and respons\$3	USPAT; US-PGPUB; EPO JPO; DERWENT; IBM_TDB	EPO;
37	BRS	742	RC adj1 constant	USPAT; US-PGPUB; EPO JPO; DERWENT; IBM_TDB	EPO; 2004/06/16
3 8	BRS	Ν	test\$3 with (wafer\$1 or IC\$1 or (integrated adj circuit\$1) or semiconductor\$1) and I/O with receiver with driver with connect\$5 and RC adj1 constant	USPAT; US-PGPUB; EPO JPO; DERWENT; IBM_TDB	EPO; 2004/06/16 ENT; 10:37
39	BRS	2	test\$3 with (wafer\$1 or IC\$1 or (integrated adj circuit\$1) or semiconductor\$1) and RC adj1 constant with I/O	USPAT; US-PGPUB; EPO JPO; DERWENT; IBM_TDB	EPO; 2004/06/16 ENT; 10:38

	Туре	Hits	Search Text	DBs	Time Stamp	Comments	Error Definiti on
40	BRS	27	test\$3 with (wafer\$1 or IC\$1 or (integrated adj circuit\$1) or semiconductor\$1) and RC adj1 constant	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/16 11:45		
41	IS&R	2	("6058496").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/16 11:03		
42	IS&R	2	("6348811").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/16 11:45		
43	BRS	Ν	<pre>chip-to-package with connection with (i/o or input/output)</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/16 11:58		
44	BRS	21	<pre>chip-to-package and connection with (i/o or input/output)</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	;2004/06/16 12:05		

	Туре	Hits	Search Text	DBs	Time Stamp	Comments
45	BRS	11	test\$3 with (wafer\$1 or IC\$1 or (integrated adj circuit\$1) or semiconductor\$1) and I/O with receiver with driver with connect\$5 and chip\$1 with (package\$1 or die or substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/16	
46	BRS	207	<pre>detect\$3 with connect\$5 with (I/O or input/output) with (semiconductor\$1 or IC\$1 or wafer\$1 or (integrated adj circuit\$1))</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/16 14:40	
47	BRS	3 1	detect\$3 with connect\$5 with (I/O or input/output) with (semiconductor\$1 or IC\$1 or wafer\$1 or (integrated adj circuit\$1)) and compar\$4 with (threshold\$1 or predetermined)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/16 14:42	
48	BRS	წ	detect\$3 with connect\$5 with (I/O or input/output) with (semiconductor\$1 or IC\$1 or wafer\$1 or (integrated adj circuit\$1)) and (differen\$2 or compar\$4) with (threshold\$1 or predetermined or reference)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/16	

51	5 0	4 9	
BRS	BRS	BRS	Туре
16	162	212	Hits
(test\$3 or detect\$3) with connect\$5 with (I/O or input/output) with (semiconductor\$1 or IC\$1 or wafer\$1 or (integrated adj circuit\$1)) and (differen\$2 or compar\$4) with (threshold\$1 or predetermined or latch\$3 or latch\$2) and fixture	(test\$3 or detect\$3) with connect\$5 with (I/O or input/output) with (semiconductor\$1 or IC\$1 or wafer\$1 or (integrated adj circuit\$1)) and (differen\$2 or compar\$4) with (threshold\$1 or predetermined or reference) and (switch\$3 or latch\$2)	(test\$3 or detect\$3) with connect\$5 with (I/O or input/output) with (semiconductor\$1 or IC\$1 or wafer\$1 or (integrated adj circuit\$1)) and (differen\$2 or compar\$4) with (threshold\$1 or predetermined or reference)	Search Text
USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	DBs
2004/06/16 14:44	2004/06/16 14:43	2004/06/16 14:42	Time Stamp
			Comments
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54 BRS	53 BRS	52 BRS	Туре
N U	773	5196	e Hits
(test\$3 or detect\$3) with connect\$5 with (I/O or input/output) with (semiconductor\$1 or IC\$1 or wafer\$1 or (integrated adj circuit\$1)) and (differen\$2 or compar\$4) with (threshold\$1 or predetermined or reference) and (switch\$3 or latch\$2) and package\$1 with chip\$1	702/117,118.ccls.	324/713,763,765,538,711.cc ls.	Search Text
USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	DBs
2004/06/17 09:09	2004/06/16 14:51	2004/06/16 14:50	Time Stamp
			Comments
			Error Definiti on

56 BRS 2	55 BRS 4	Type Hits	
t\$5 with (I/O or output) with onductor\$1 or IC\$ er\$1 or (integrat rcuit\$1)) and driensitive with tance 3 or detect\$3) with ty5 with (I/O or output) with	(test\$3 or detect\$3) with connect\$5 with (I/O or input/output) with (semiconductor\$1 or IC\$1 or wafer\$1 or (integrated adj circuit\$1)) and (differen\$2 or compar\$4) with (threshold\$1 or predetermined or reference) and (switch\$3 or latch\$2) and package\$1 with chip\$1 and driver\$1 with receiver\$1	Search Text	
USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; USPAT;	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	DBs	
2004/06/17	2004/06/16	Time Stamp	
		Comments Definiti	

	55 80	5 9	60	
Туре	BRS 5	BRS 7	BRS	BBC S
Hits			0	(te con inp se or
Search Text	(test\$3 or detect\$3) with connect\$5 with (I/O or input/output) with (semiconductor\$1 or IC\$1 or wafer\$1 or (integrated adj circuit\$1)) and driver with capacitance	(test\$3 or detect\$3) with connect\$5 with (I/O or input/output) with (semiconductor\$1 or IC\$1 or wafer\$1 or (integrated adj circuit\$1)) and weak with driver	(test\$3 or detect\$3) with connect\$5 with (I/O or input/output) with (semiconductor\$1 or IC\$1 or wafer\$1 or (integrated adj circuit\$1)) and driver with deliver\$3 with (current or capacit\$4 or load\$3)	(test\$3 or detect\$3) with connect\$5 with (I/O or input/output) with (semiconductor\$1 or IC\$1
DBs	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
Time Stamp	2004/06/17 09:19	2004/06/17 09:42	2004/06/17 09:41	2004/06/17
Comments				
Error Definiti on				

•	Туре	Hits	Search Text	DBs	Time Stamp	Comments
62	BRS	31	(test\$3 or detect\$3) with connect\$5 with (I/O or input/output) with (semiconductor\$1 or IC\$1 or wafer\$1 or (integrated adj circuit\$1)) and delay with driver\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/17 10:11	
63	BRS	ហ	(test\$3 or detect\$3) with connect\$5 with (I/O or input/output) with (semiconductor\$1 or IC\$1 or wafer\$1 or (integrated adj circuit\$1)) and delay with driver\$1 with (current\$1 or capacit\$4 or load\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/17	
64	BRS	Н	"6480817".PN.	USPAT	2004/06/17 10:10	
65	BRS	Н	"6292766".PN.	USPAT	2004/06/17 10:10	
6	BRS	0	6662352.uref.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/17 10:11	-
67	BRS	8	(test\$3 or detect\$3) with connect\$5 with (I/O or input/output) with (semiconductor\$1 or IC\$1 or wafer\$1 or (integrated adj circuit\$1)) and additional with imped\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/17 10:48	

connect\$5 with (I input/output) wit. (gemiconductor\$1 or wafer\$1 or (in adj circuit\$1)) and imped\$4 with conn (test\$3 or detect connect\$5 with (I input/output) wit. (gemiconductor\$1 or wafer\$1 or (in adj circuit\$1)) and driver with imped connection 70 BRS 2 "20020169588" 71 BRS 2 "20020046374"		Туре	Hits	Search Text (test\$3 or detect\$3) with	DBs	Time Stamp
(test\$3 or deficonnect\$5 with input/output) (semiconductoring adj circuit\$1 or adj circuit\$1 driver with inconnection BRS 2 "20020169588" BRS 2 "20020046374"		BRS	37	est\$3 or detect\$3) with inect\$5 with (I/O or out/output) with miconductor\$1 or IC\$1 wafer\$1 or (integrated circuit\$1) and bed\$4 with connection	USPAT; US-PGPUB; EP JPO; DERWENT IBM_TDB	EPO; 2004/06/17 VENT; 10:49
BRS 2 BRS 2 BRS 2	59	BRS	4	detect\$3) with ith (I/O or t) with tor\$1 or IC\$1 or (integrated \$1)) and imped\$4 with	USPAT; US-PGPUB; EP JPO; DERWENT IBM_TDB	; EPO; WENT;
BRS 2	70	BRS	2		USPAT; US-PGPUB; EPO JPO; DERWENT IBM_TDB	; EPO; 2004/06/17 WENT; 12:30
BRS 2	71	BRS	N		USPAT; US-PGPUB; EP JPO; DERWENT IBM_TDB	3; EPO; 2004/06/17 RWENT; 12:31
	72	BRS	Ν	,	USPAT; US-PGPUB; EP JPO; DERWENT IBM_TDB	; EPO;